

200mA Negative Voltage Regulator with ON/OFF Control

■ GENERAL DESCRIPTION

The XC6901 Series is a negative voltage CMOS regulator which includes a reference voltage source, error amplifier, driver transistor, current limiter and phase compensator.

The CE function enables the circuit to be in stand-by mode by inputting low level signal. In the stand-by mode, the electric charge at the output capacitor (C_L) will be discharged via the internal auto-discharge switch and as a result the $-V_{OUT}$ pin quickly returns to the V_{SS} level.

The over current protection circuit will operate when the output current reaches limit current. The thermal shutdown circuit will operate when the junction temperature reaches limit temperature.

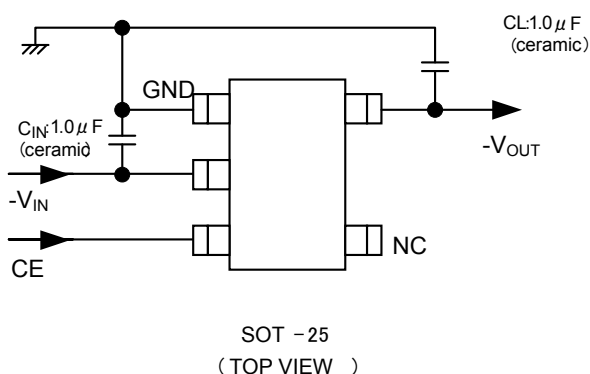
■ APPLICATIONS

- Negative power supplies
- Modules (Wireless LAN, Digital still cameras, etc)
- Digital still cameras
- Mobile devices / terminals

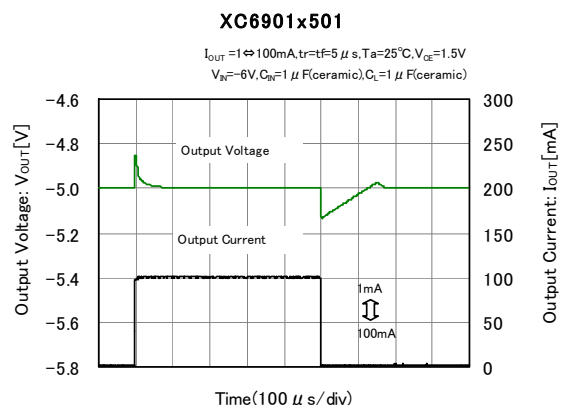
■ FEATURES

| | |
|--------------------------------------|-----------------------------------------------------------------------------------|
| Maximum Output Current | : 200mA |
| Input Voltage Range | : -2.4V ~ -12.4V ($V_{CE}=3.6V$) |
| Output Voltage Range | : -0.9V ~ -12.0V |
| Accuracy | : $\pm 1.5\%$ ($V_{OUT} < -2.0V$) $\pm 0.03V$ ($V_{OUT} \geq -2.0V$) |
| Temperature Stability | : TYP. $\pm 50ppm/^{\circ}C$ |
| CE High Level Voltage | : +1.2V ~ +3.6V, (Active High) |
| Dropout Voltage | : 400mV @ $I_{OUT}=100mA$ |
| Low Power Consumption | : 100 μA MAX. |
| Stand-by Current | : Less than 0.1 μA |
| Protection Circuits | : Current Limit 350mA TYP, Foldback Overheat Protection $T_{TSB}=150^{\circ}C$ |
| Output Capacitor | : Ceramic Capacitor Compatible |
| Built-in Function | : C_L High-Speed Discharge |
| Operating Ambient Temperature | : $-40^{\circ}C \sim +85^{\circ}C$ |
| Packages | : SOT-25, SOT-89-5, USP-6C |
| Environmentally Friendly | : EU RoHS Compliant, Pb Free |

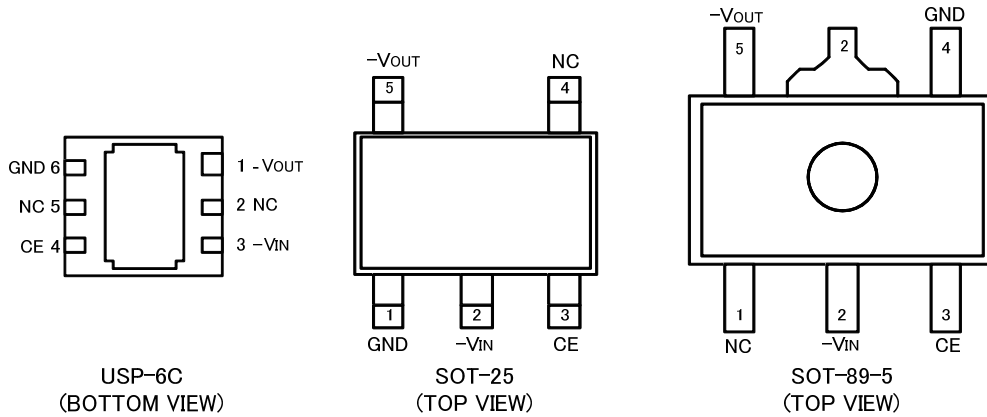
■ TYPICAL APPLICATION CIRCUIT



■ TYPICAL PERFORMANCE CHARACTERISTICS



PIN CONFIGURATION



* The dissipation pad for the USP-6C package should be solder-plated in recommended mount pattern and metal masking to enhance mounting strength and heat release. If the pad needs to be connected to other pins, it should be connected to the -V_{IN} (No. 3) pin.

PIN ASSIGNMENT

| PIN NUMBER | | | PIN NAME | FUNCTIONS |
|------------|--------|----------|-------------------|-----------------------|
| USP-6C | SOT-25 | SOT-89-5 | | |
| 1 | 5 | 5 | -V _{OUT} | Negative Output |
| 2,5 | 4 | 1 | NC | No Connection |
| 3 | 2 | 2 | -V _{IN} | Negative Supply Input |
| 4 | 3 | 3 | CE | ON/OFF Control |
| 6 | 1 | 4 | GND | Ground |

FUNCTION CHART

XC6901 Series D type

| PIN NAME | SIGNAL | STATUS |
|----------|--------|----------|
| CE | L | Stand-by |
| | H | Active |
| | OPEN | Stand-by |

■ PRODUCT CLASSIFICATION

● Ordering Information

XC6901①②③④⑤⑥-⑦^(*) ON/OFF Control Voltage Regulator (CE Active High)

| DESIGNATOR | ITEM | SYMBOL | DESCRIPTION |
|------------|--------------------------|--------|-------------------------------------------------------------------------|
| ① | Type ⁽²⁾ | D | CE Pull-down resistor C _L Auto-discharge |
| ②③ | Output Voltage | 09~C0 | -0.9V~-12V e.g. -0.9V→②=0, ③=9, -12V→②=C, ③=0 A: 10, B: 11, C: 12 |
| ④ | Output Type | 1 | 0.10V Increments e.g. -1.2V→②=1, ③=2, ④=1 |
| | | B | 0.05V Increments for -0.95V~-4.95V e.g. -1.25V→②=1, ③=2, ④=B |
| ⑤⑥-⑦ | Packages (Order Unit) | ER-G | USP-6C (3,000/Reel) |
| | | MR-G | SOT-25 (3,000/Reel) |
| | | PR-G | SOT-89-5 (1,000/Reel) |

^(*) The "-G" suffix denotes Halogen and Antimony free as well as being fully EU RoHS compliant.

⁽²⁾ For the type without C_L auto-discharge, please contact your local Torex sales office or representative.

■ STANDARD VOLTAGE

● Examples for standard voltage

| V _{OUT} (V) | PACKAGES | | |
|-------------------------|----------------|----------------|----------------|
| | USP-6C | SOT-25 | SOT-89-5 |
| -1.2V | XC6901D121ER-G | XC6901D121MR-G | XC6901D121PR-G |
| -2.5V | XC6901D251ER-G | XC6901D251MR-G | XC6901D251PR-G |
| -2.6V | XC6901D261ER-G | XC6901D261MR-G | XC6901D261PR-G |
| -3.0V | XC6901D301ER-G | XC6901D301MR-G | XC6901D301PR-G |
| -3.3V | XC6901D331ER-G | XC6901D331MR-G | XC6901D331PR-G |
| -4.0V | XC6901D401ER-G | XC6901D401MR-G | XC6901D401PR-G |
| -4.5V | XC6901D451ER-G | XC6901D451MR-G | XC6901D451PR-G |
| -5.0V | XC6901D501ER-G | XC6901D501MR-G | XC6901D501PR-G |
| -6.0V | XC6901D601ER-G | XC6901D601MR-G | XC6901D601PR-G |
| -12.0V | XC6901DC01ER-G | XC6901DC01MR-G | XC6901DC01PR-G |

■ ABSOLUTE MAXIMUM RATINGS

GND=0V, Ta=25°C

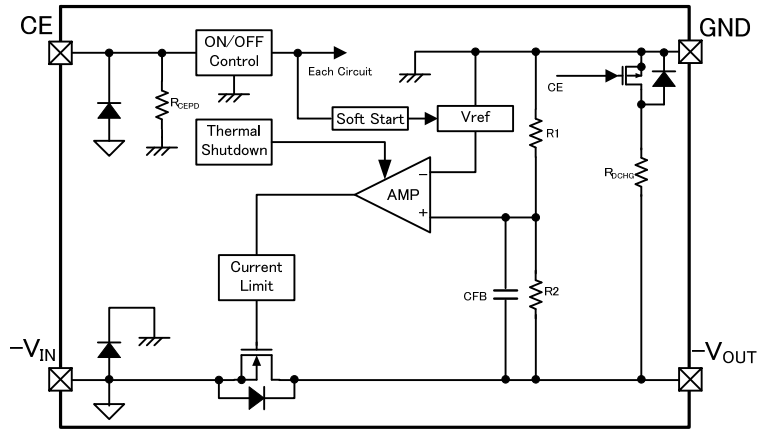
| PARAMETER | | SYMBOL | RATINGS | UNITS |
|------------------------------------|----------|-----------|------------------------------------|-------|
| Input Voltage | | V_{IN} | GND-18+ V_{CE} ~ GND+0.3 | V |
| Output Current | | I_{OUT} | 500 ^(*1) | mA |
| Output Voltage | | V_{OUT} | - V_{IN} -0.3 ~ GND+0.3 | V |
| CE Input Voltage | | V_{CE} | GND-0.3 ~ V_{IN} +18 | V |
| Power Dissipation | USP-6C | Pd | 120 | mW |
| | | | 1000 (PCB mounted) ^(*2) | |
| | SOT-25 | | 250 | |
| | | | 600 (PCB mounted) ^(*2) | |
| | SOT-89-5 | | 500 | |
| 1300 (PCB mounted) ^(*2) | | | | |
| Operating Ambient Temperature | | Topr | -40~+85 | °C |
| Storage Temperature | | Tstg | -55~+125 | °C |

(*1): Please use within the range of $I_{OUT} \leq Pd / (V_{OUT} - V_{IN})$

(*2) The power dissipation figure shown is PCB mounted and is for reference only. Please refer to page 24~26 for details.

■ BLOCK DIAGRAM

XC6901 Series D type



*Diodes inside the circuit are an ESD protection diode and a parasitic diode.

ELECTRICAL CHARACTERISTICS

●XC6901 Series

GND=0V, Ta=25°C

| PARAMETER | SYMBOL | CONDITIONS | | MIN. | TYP. | MAX. | UNITS | CIRCUIT |
|--------------------------------------------|---------------------------------------------------------|----------------------------------------------------------------------|-------------------------|----------------|-----------------------------|----------------|------------|---------|
| Output Voltage | $V_{OUT(E)}$ ⁽²⁾ | $I_{OUT}=20mA$ | $V_{OUT(T)} < -2.0V$ | $\times 1.015$ | $V_{OUT(T)}$ ⁽¹⁾ | $\times 0.985$ | V | ① |
| | | | $V_{OUT(T)} \geq -2.0V$ | -0.030 | | +0.030 | | |
| Maximum Output Current ⁽⁴⁾ | I_{OUTMAX} | $V_{IN}=V_{OUT(T)}-2.0V$ | $V_{OUT(T)} \leq -2.4V$ | 200 | - | - | mA | ① |
| | | $V_{IN}=-4.4V$ | $V_{OUT(T)} > -2.4V$ | | | | | |
| Load Regulation | ΔV_{OUT} | $V_{IN}=V_{OUT(T)}-1.0V$ | $V_{OUT(T)} \leq -3.0V$ | - | 20 | 60 | mV | ① |
| | | $V_{IN}=-4.0V$ | $V_{OUT(T)} > -3.0V$ | | | | | |
| | | $1mA \leq I_{OUT} \leq 100mA$ | | | | | | |
| Dropout Voltage | V_{dif} ⁽³⁾ | $I_{OUT}=20mA$ | | - | $E-1$ ⁽⁵⁾ | | mV | ① |
| Supply Current | I_{BIAS} | $V_{IN}=-14.5V, V_{CE}=1.5V, I_{OUT}=0mA$ | | - | 100 | 200 | μA | ① |
| Stand-by Current | I_{STB} | $V_{IN}=-14.5V, V_{CE}=0V, I_{OUT}=0mA$ | | - | 0.01 | 0.1 | μA | ① |
| Input Line Regulation | $\frac{\Delta V_{OUT}}{(\Delta V_{IN} \cdot V_{OUT})}$ | $-14.5V \sim V_{OUT(T)}-1V$ | $V_{OUT(T)} \leq -1.4V$ | - | 0.01 | 0.20 | %V | ① |
| | | $-14.5V \sim -2.4V$ | $V_{OUT(T)} > -1.4V$ | | | | | |
| | | $I_{OUT}=20mA$ | | | | | | |
| Input Voltage | V_{IN} | | | $-16+V_{CE}$ | - | -2.4 | V | ① |
| Output Voltage Temperature Characteristics | $\frac{\Delta V_{OUT}}{(\Delta T_{opr} \cdot V_{OUT})}$ | $I_{OUT}=20mA$ $-40^\circ C \leq T_{opr} \leq 85^\circ C$ | | - | ± 50 | - | ppm/°C | ① |
| Power Supply Rejection Ratio | PSRR | $V_{IN} = \{V_{OUT(T)} - 1.0\} + 0.5V_{p-pAC}, I_{OUT}=20mA, f=1kHz$ | | - | 45 | - | dB | ② |
| Limit Current | I_{LIM} | $V_{IN}=V_{OUT(T)}-2.0V$ | $V_{OUT(T)} \leq -2.4V$ | 210 | 300 | - | mA | ① |
| | | $V_{IN}=-4.4V$ | $V_{OUT(T)} > -2.4V$ | | | | | |
| Short-Circuit Current | I_{SHORT} | $V_{IN}=V_{OUT(T)}-2.0V$ Short - V_{OUT} to GND level | | - | 80 | - | mA | ① |
| Detect Thermal Shutdown Temperature | T_{TSD} | IC Junction temperature | | - | 150 | - | °C | ① |
| Release Thermal Shutdown Temperature | T_{TSR} | IC Junction temperature | | - | 125 | - | °C | ① |
| Hysteresis Width | T_{HYS} | $T_{TSD} - T_{TSR}$ | | - | 25 | - | °C | ① |
| CE "H" Level Voltage | V_{CEH} | | | 1.2 | - | 3.6 | V | ① |
| CE "L" Level Voltage | V_{CEL} | | | GND | - | 0.4 | V | ① |
| CE "H" Level Current | I_{CEH} | $V_{IN}=-12.4V, V_{CE}=3.6V$ | XC6901D Series | 1.8 | 4 | 7 | μA | ① |
| CE "L" Level Current | I_{CEL} | $V_{CE}=GND$ | | -0.1 | - | 0.1 | μA | ① |
| C_L Discharge Resistor | R_{DCHG} | $V_{IN}=-8V, V_{OUT}=-2V, V_{CE}=GND$ | | 0.7 | 1.2 | 1.8 | k Ω | ① |
| Soft Start Time | t_{SS} | $R_L=3k\Omega, Rise Time$ CE="H" to 95% of $V_{OUT(E)}$ | $V_{OUT(T)} > -4.0V$ | 0.15 | 0.4 | 1.2 | ms | ③ |
| | | | $V_{OUT(T)} \leq -4.0V$ | 0.3 | 0.7 | 2 | ms | ③ |

NOTE: Unless otherwise stated regarding input voltage conditions $V_{CE}=1.5V, GND=0V, V_{IN}=V_{OUT(T)}-1.0V$ or $-2.4V$ the one which bigger absolute value.

*1) $V_{OUT(T)}$: Nominal output voltage

*2) $V_{OUT(E)}$: Effective output voltage (see the voltage chart)

(ie. The output voltage when " $V_{OUT(T)}-1.0V$ " or " $-2.4V$ " is provided at the V_{IN} pin while maintaining a certain I_{OUT} value.

*3) $V_{dif} = -\{V_{IN1} - V_{OUT1}\}$

V_{IN1} is the input voltage when V_{OUT1} appears at the V_{OUT} pin while input voltage is gradually increased

V_{OUT1} is the voltage equal to 98% of the normal output voltage when amply stabilized $V_{OUT(T)}-1.0V$ or $-2.4V$ (the bigger absolute value one) are input at the V_{IN} pin.

*4) The maximum current may not be able to flow when thermal shutdown operates, it depends on power dissipation.

*5) E-1: Refer to dropout voltage chart.

■ ELECTRICAL CHARACTERISTICS(Continued)

Dropout Voltage Chart ($V_{OUT(T)} = -0.9V \sim -5V$)

| NOMINAL OUTPUT VOLTAGE | E-1 | | NOMINAL OUTPUT VOLTAGE | E-1 | | NOMINAL OUTPUT VOLTAGE | E-1 | |
|------------------------------|-----------------|------|------------------------------|-----------------|------|------------------------------|-----------------|------|
| | DROPOUT VOLTAGE | | | DROPOUT VOLTAGE | | | DROPOUT VOLTAGE | |
| | Vdif (mV) | | | Vdif (mV) | | | Vdif (mV) | |
| $V_{OUT(T)}$ | TYP. | MAX. | $V_{OUT(T)}$ | TYP. | MAX. | $V_{OUT(T)}$ | TYP. | MAX. |
| -0.90 | 800 | 1500 | -2.85 | 116 | 157 | -4.80 | 80 | 115 |
| -0.95 | 750 | 1450 | -2.90 | 114 | 155 | -4.85 | 80 | 115 |
| -1.00 | 700 | 1400 | -2.95 | 112 | 153 | -4.90 | 79 | 115 |
| -1.05 | 650 | 1350 | -3.00 | 110 | 151 | -4.95 | 79 | 115 |
| -1.10 | 600 | 1300 | -3.05 | 109 | 150 | -5.00 | 78 | 114 |
| -1.15 | 550 | 1250 | -3.10 | 108 | 148 | | | |
| -1.20 | 500 | 1200 | -3.15 | 107 | 147 | | | |
| -1.25 | 450 | 1150 | -3.20 | 105 | 145 | | | |
| -1.30 | 400 | 1100 | -3.25 | 104 | 144 | | | |
| -1.35 | 350 | 1050 | -3.30 | 102 | 142 | | | |
| -1.40 | 300 | 1000 | -3.35 | 102 | 141 | | | |
| -1.45 | 270 | 950 | -3.40 | 101 | 140 | | | |
| -1.50 | 230 | 900 | -3.45 | 101 | 139 | | | |
| -1.55 | 220 | 850 | -3.50 | 100 | 137 | | | |
| -1.60 | 210 | 800 | -3.55 | 99 | 136 | | | |
| -1.65 | 205 | 750 | -3.60 | 98 | 135 | | | |
| -1.70 | 200 | 700 | -3.65 | 97 | 134 | | | |
| -1.75 | 195 | 650 | -3.70 | 95 | 133 | | | |
| -1.80 | 190 | 600 | -3.75 | 95 | 132 | | | |
| -1.85 | 183 | 550 | -3.80 | 94 | 131 | | | |
| -1.90 | 176 | 500 | -3.85 | 94 | 130 | | | |
| -1.95 | 171 | 450 | -3.90 | 93 | 129 | | | |
| -2.00 | 165 | 400 | -3.95 | 92 | 128 | | | |
| -2.05 | 161 | 350 | -4.00 | 91 | 127 | | | |
| -2.10 | 156 | 300 | -4.05 | 90 | 126 | | | |
| -2.15 | 152 | 250 | -4.10 | 89 | 125 | | | |
| -2.20 | 148 | 200 | -4.15 | 89 | 125 | | | |
| -2.25 | 144 | 187 | -4.20 | 88 | 124 | | | |
| -2.30 | 140 | 185 | -4.25 | 87 | 123 | | | |
| -2.35 | 138 | 183 | -4.30 | 86 | 122 | | | |
| -2.40 | 135 | 181 | -4.35 | 86 | 122 | | | |
| -2.45 | 132 | 178 | -4.40 | 85 | 121 | | | |
| -2.50 | 129 | 174 | -4.45 | 85 | 120 | | | |
| -2.55 | 127 | 172 | -4.50 | 84 | 119 | | | |
| -2.60 | 125 | 169 | -4.55 | 83 | 119 | | | |
| -2.65 | 123 | 166 | -4.60 | 82 | 119 | | | |
| -2.70 | 121 | 163 | -4.65 | 82 | 118 | | | |
| -2.75 | 119 | 161 | -4.70 | 82 | 117 | | | |
| -2.80 | 117 | 159 | -4.75 | 81 | 116 | | | |

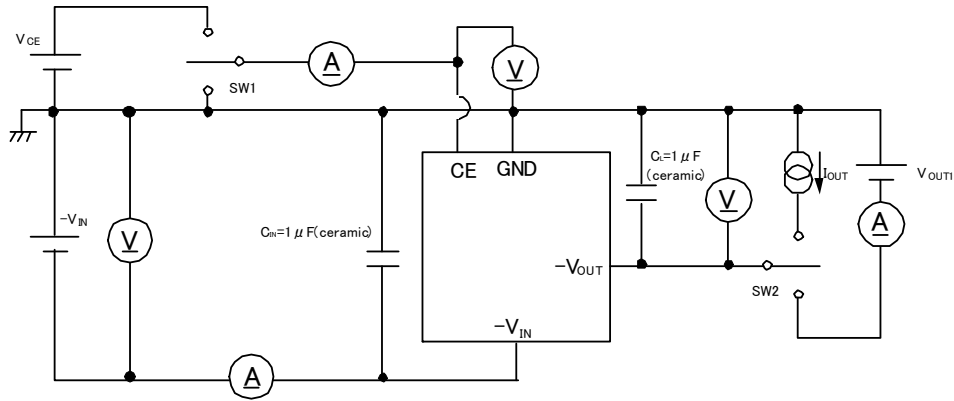
ELECTRICAL CHARACTERISTICS(Continued)

Dropout Voltage Chart ($V_{OUT(T)} = -5.1V \sim -12V$)

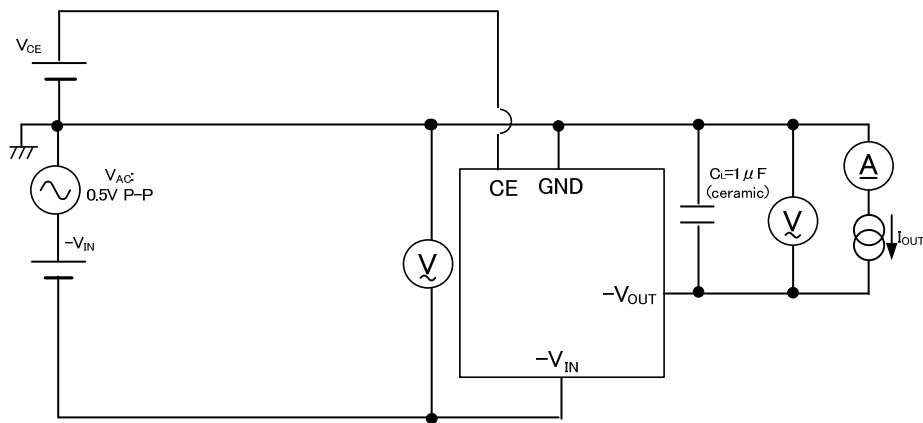
| NOMINAL OUTPUT VOLTAGE | E-1 | | NOMINAL OUTPUT VOLTAGE | E-1 | |
|------------------------------|-----------------|------|------------------------------|-----------------|------|
| | DROPOUT VOLTAGE | | | DROPOUT VOLTAGE | |
| | Vdif(mV) | | | Vdif(mV) | |
| $V_{OUT(T)}$ | TYP. | MAX. | $V_{OUT(T)}$ | TYP. | MAX. |
| -5.1 | 77 | 113 | -9.0 | 58 | 93 |
| -5.2 | 77 | 112 | -9.1 | 58 | 92 |
| -5.3 | 76 | 111 | -9.2 | 58 | 92 |
| -5.4 | 75 | 110 | -9.3 | 57 | 92 |
| -5.5 | 74 | 110 | -9.4 | 57 | 91 |
| -5.6 | 73 | 109 | -9.5 | 56 | 91 |
| -5.7 | 73 | 108 | -9.6 | 56 | 91 |
| -5.8 | 72 | 107 | -9.7 | 56 | 91 |
| -5.9 | 71 | 106 | -9.8 | 55 | 90 |
| -6.0 | 70 | 105 | -9.9 | 55 | 90 |
| -6.1 | 70 | 105 | -10.0 | 54 | 90 |
| -6.2 | 69 | 104 | -10.1 | 54 | 90 |
| -6.3 | 69 | 104 | -10.2 | 54 | 89 |
| -6.4 | 68 | 103 | -10.3 | 54 | 89 |
| -6.5 | 67 | 102 | -10.4 | 54 | 89 |
| -6.6 | 66 | 102 | -10.5 | 53 | 88 |
| -6.7 | 66 | 101 | -10.6 | 53 | 88 |
| -6.8 | 65 | 101 | -10.7 | 53 | 88 |
| -6.9 | 65 | 100 | -10.8 | 53 | 88 |
| -7.0 | 65 | 100 | -10.9 | 53 | 88 |
| -7.1 | 64 | 99 | -11.0 | 52 | 88 |
| -7.2 | 64 | 99 | -11.1 | 53 | 88 |
| -7.3 | 63 | 98 | -11.2 | 52 | 87 |
| -7.4 | 63 | 98 | -11.3 | 51 | 87 |
| -7.5 | 62 | 98 | -11.4 | 51 | 87 |
| -7.6 | 62 | 98 | -11.5 | 50 | 87 |
| -7.7 | 62 | 97 | -11.6 | 50 | 87 |
| -7.8 | 61 | 96 | -11.7 | 50 | 87 |
| -7.9 | 61 | 96 | -11.8 | 50 | 87 |
| -8.0 | 60 | 96 | -11.9 | 50 | 87 |
| -8.1 | 60 | 96 | -12.0 | 50 | 87 |
| -8.2 | 60 | 95 | | | |
| -8.3 | 60 | 95 | | | |
| -8.4 | 60 | 94 | | | |
| -8.5 | 59 | 94 | | | |
| -8.6 | 59 | 94 | | | |
| -8.7 | 59 | 94 | | | |
| -8.8 | 59 | 93 | | | |
| -8.9 | 59 | 93 | | | |

TEST CIRCUITS

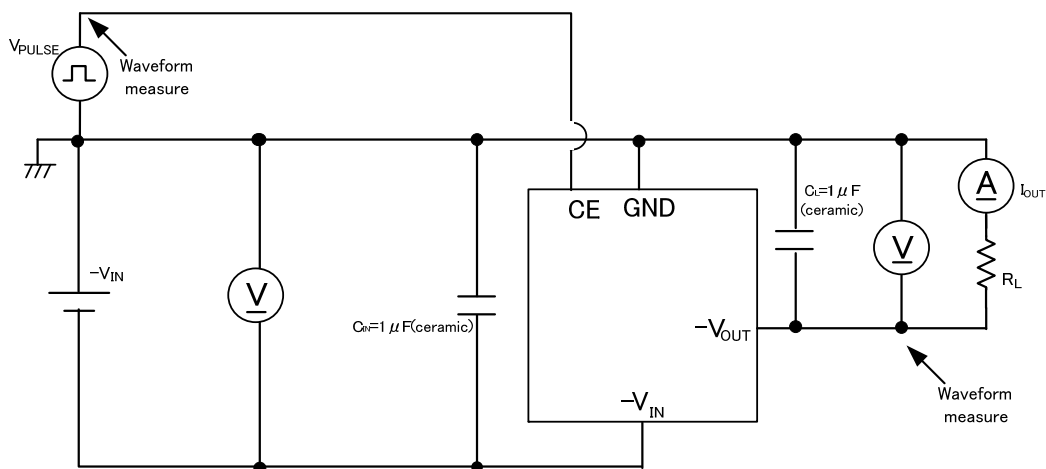
1) CIRCUIT①



2) CIRCUIT②

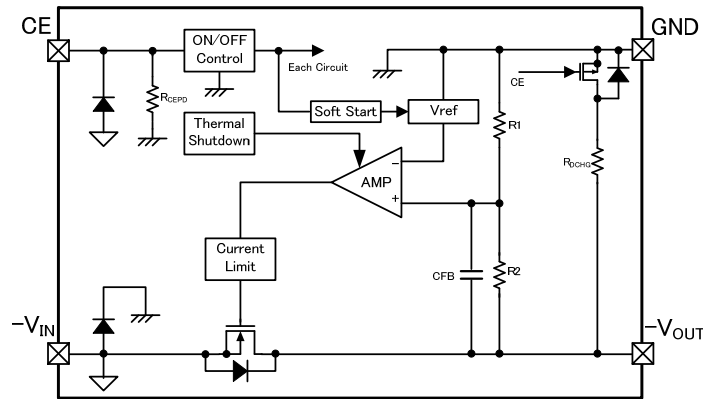


3) CIRCUIT③



OPERATIONAL EXPLANATION

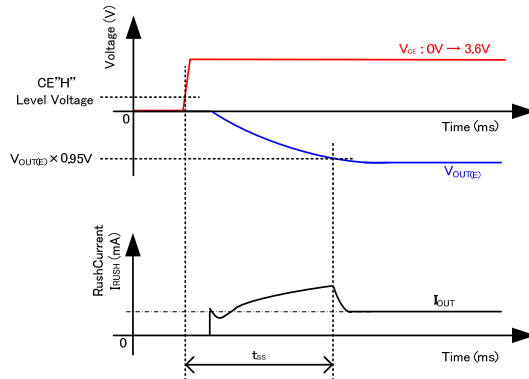
The voltage divided by resistors R1 and R2 is compared with the internal reference voltage based on ground by the error amplifier. The driver transistor tied to the $-V_{IN}$ pin is then driven by the subsequent output signal. The output voltage at the $-V_{OUT}$ pin is controlled and stabilized by a system of negative feedback.



<Soft Start Function>

XC6901 Series includes soft-start circuit. During power start-up, the inrush current from $-V_{IN}$ pin to V_{OUT} pin to charge C_L capacitor can be reduced and it makes the V_{IN} stable. Soft-start time (t_{SS}) is optimized internally.

Figure1 : Soft Start Time and Inrush Current



<Current Limit, Short-Circuit Protection>

The XC6901 series' fold-back circuit operates as an output current limiter and a short protection circuit for the output pin. When the output current reaches the current limit level, output voltage drops with the decrease of the output current. There are no parasitic diode between the $-V_{OUT}$ pin and GND pin. The minimized short-circuit current is maintained even if the $-V_{OUT}$ pin voltage is pulled up toward positive.

<Thermal Shutdown>

The XC6901 Series has an internal thermal Shutdown(TSD) circuit for protection against overheating. When the junction temperature reaches the detection temperature, the driver transistor is forcibly turned off. When the junction temperature falls to the release temperature with the driver transistor still in the off state, the driver transistor turns on (automatic recovery) and restarts regulator operation.

<CE Pin>

The XC6901 Series is able to shut down the regulator circuit using the CE pin signal. CE pin can be controlled with positive voltage due to P-channel transistor source input (Gate is grounded). A current flow of a few micro amperes. The regulator is turned on when CE input voltage is positive, the regulator is turned off when CE input is GND.

When CE pin is open, IC is turned OFF, due to the built-in Pull-down resistor. When the IC is turned OFF with low input voltage to the CE pin, $-V_{OUT}$ pin voltage goes into GND level by R1, R2 and CL discharge resistance(R_{DCHG}).

■ OPERATIONAL EXPLANATION(Continued)

<C_L High Speed Discharge>

The XC6901D type is capable of high-speed discharge of the charge that collects on the output capacitor (C_L below). This is accomplished by the P-channel MOSFET and C_L discharge resistance connected between the -V_{OUT} and GND pins in the block diagram, and takes place when the L-level signal (IC internal circuit shutdown signal) of the CE pin is input so that it could avoid malfunction.

The C_L discharge time is determined by this C_L discharge resistance and C_L. Letting the time constant of the C_L discharge resistance R_{DCHG} and C_L be τ ($\tau = C \times R$), the output voltage after discharge by the P-channel MOSFET can be obtained from the CR discharge equation below. Please be noted that R_{DCHG} varies with supply voltage and V_{DS}(drain-source voltage) since it consists of P-channel MOSFET.

$$t = \tau \ln (V_{OUT(E)} / V)$$

V: Output voltage during discharge

V_{OUT(E)}: Output voltage

t: Discharge time

τ : C_L auto-discharge resistance R_{DCHG} × C_L Output capacitor value C_L

<Low ESR Capacitor>

With the XC6901 series, a stable output voltage is achievable even if used with low ESR capacitors, as a phase compensation circuit is built-in. The output capacitor (C_L) should be connected as close to -V_{OUT} pin and GND pin to obtain stable phase compensation. Values required for the phase compensation are as the table below.

For a stable power input, please connect an input capacitor (C_{IN}) near power supply. In order to ensure the stable phase compensation while avoiding run-out of values, please use the capacitor (C_{IN}, C_L) which does not depend on bias or temperature too much. The table below shows recommended values of C_{IN}, C_L for all environment conditions.

CHART 1 : Recommended Values of C_{IN}, C_L (MIN.)

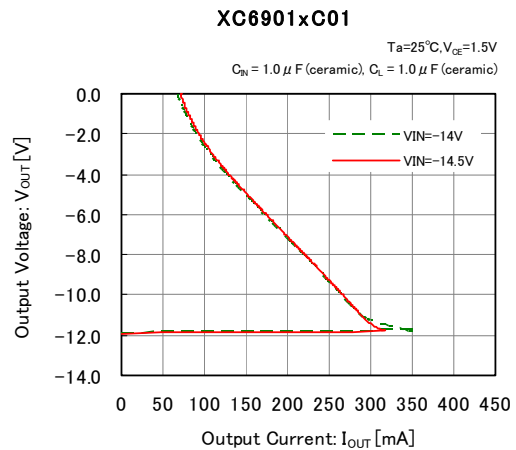
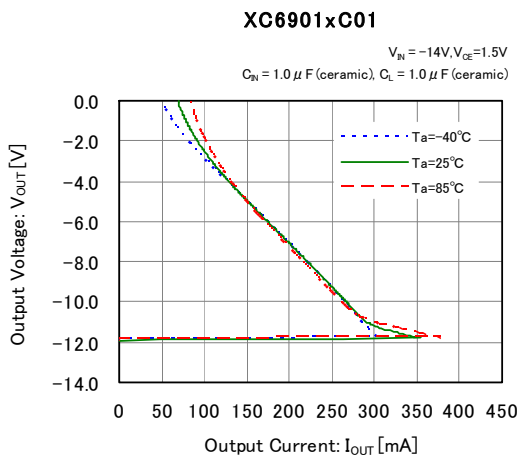
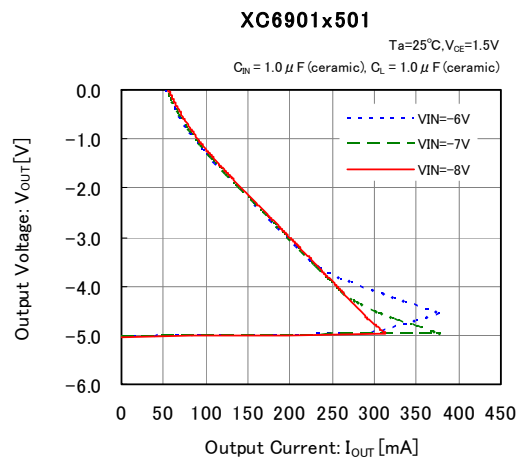
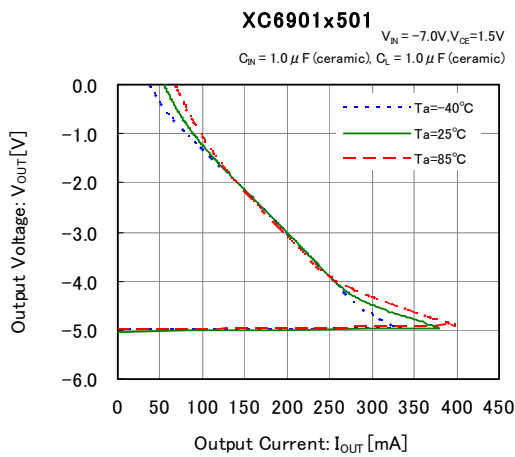
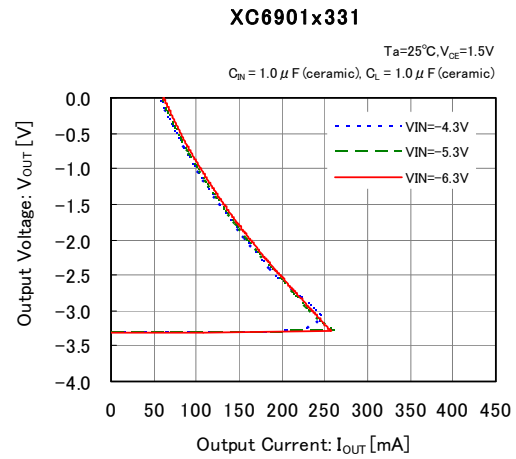
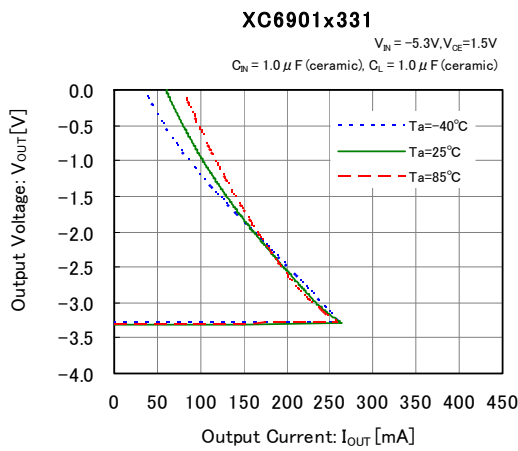
| OUTPUT VOLTAGE RANGE | INPUT CAPACITOR | OUTPUT CAPACITOR |
|----------------------|-----------------|------------------|
| V _{OUT(T)} | C _{IN} | C _L |
| -0.9V~-12V | 1.0 μF~ | 1.0 μF~100 μF |

■ NOTE ON USE

- 1) For temporary, transitional voltage drop or voltage rising phenomenon. The IC is liable to malfunction should the ratings be exceeded.
- 2) Where wiring impedance is high, operations may become unstable due to noise and/or phase lag depending on output current. Please enforce wiring $-V_{IN}$ and GND.
- 3) Please wire the C_{IN} and C_L as close to the IC as possible.
- 4) Capacitances of these capacitors (C_{IN} , C_L) are decreased by the influences of bias voltage and ambient temperature. Care shall be taken for capacitor selection to ensure stability of phase compensation from the point of ESR influence.
- 5) Torex places an importance on improving our products and its reliability. However, by any possibility, we would request user fail-safe design and post-aging treatment on system or equipment.

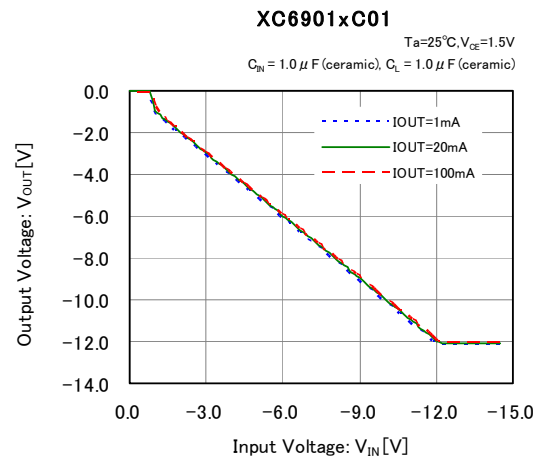
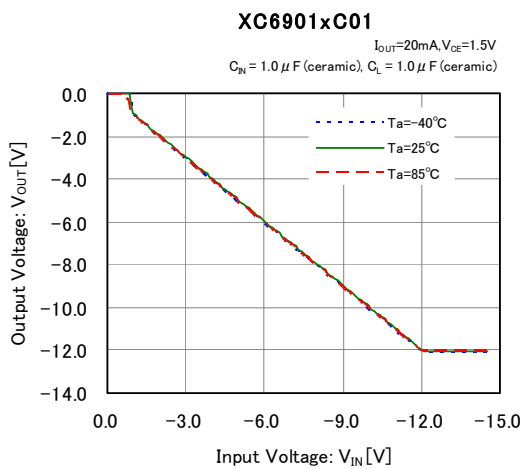
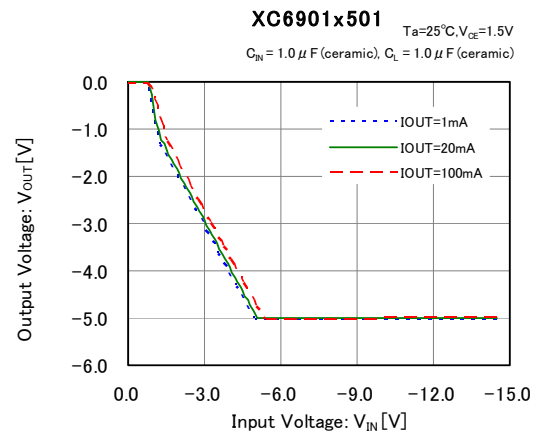
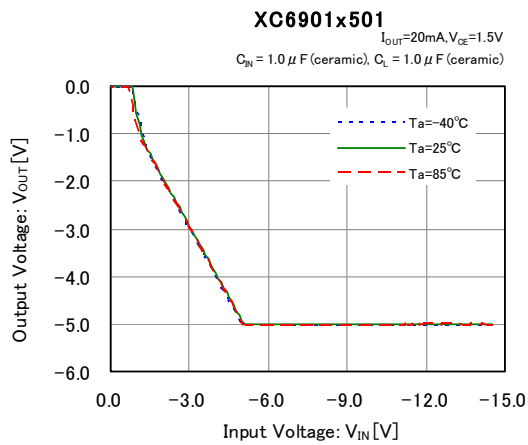
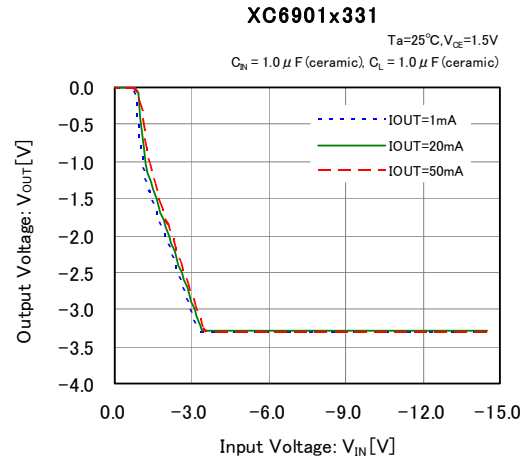
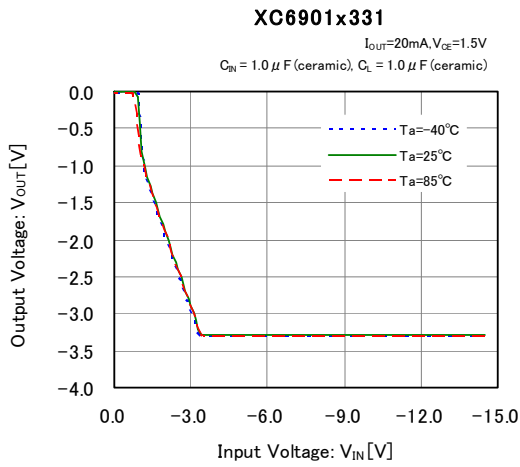
TYPICAL PERFORMANCE CHARACTERISTICS

(1) Output Voltage vs. Output Current



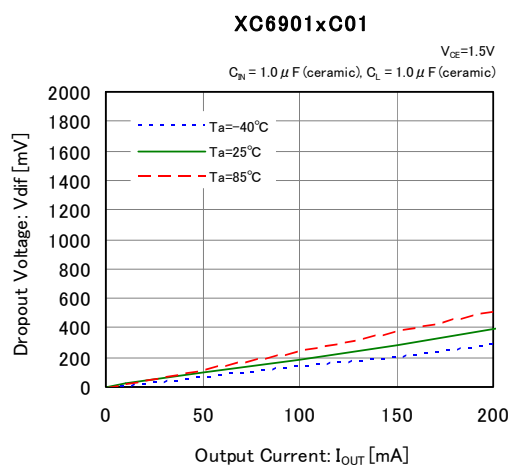
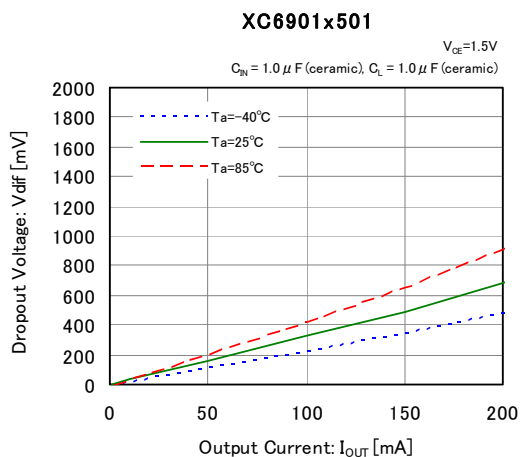
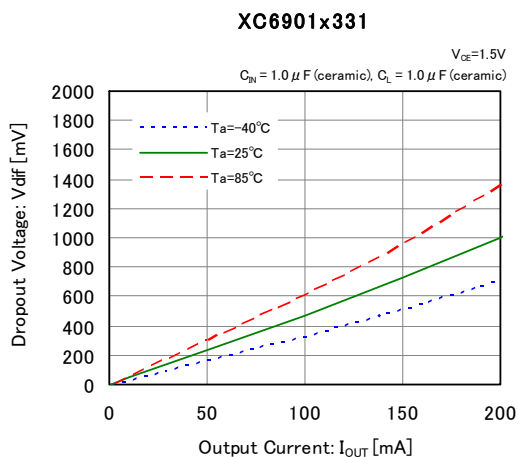
TYPICAL PERFORMANCE CHARACTERISTICS (Continued)

(2) Output Voltage vs. Input Voltage

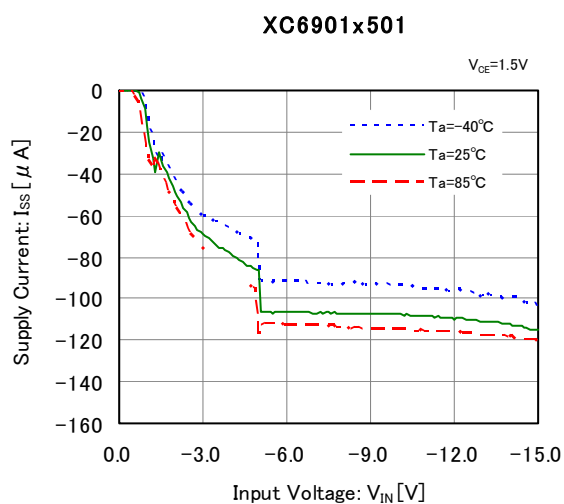
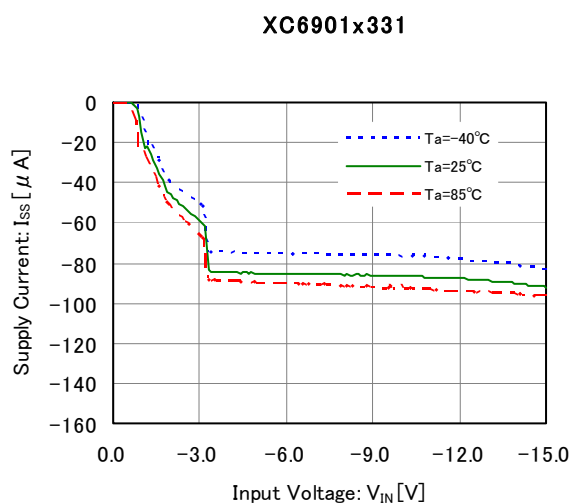


TYPICAL PERFORMANCE CHARACTERISTICS (Continued)

(3) Dropout Voltage vs. Output Current

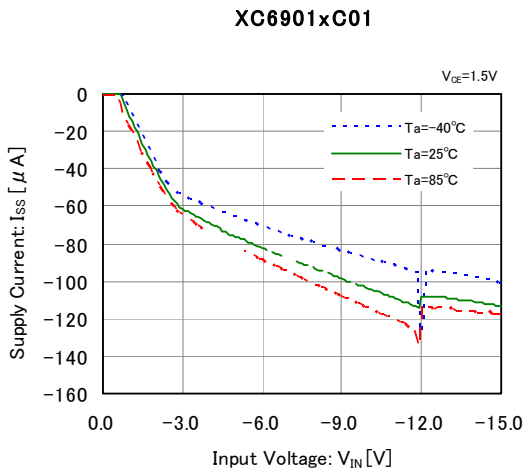


(4) Supply Current vs. Input Voltage

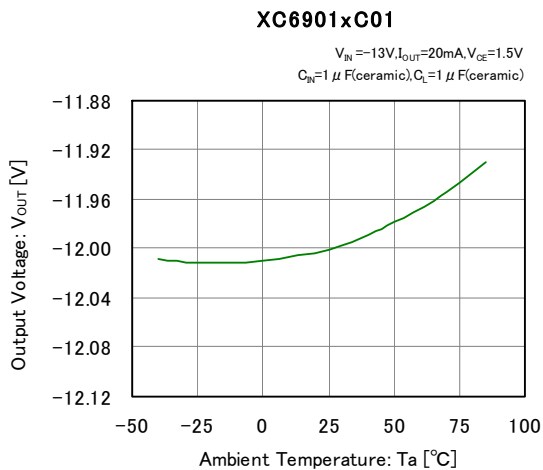
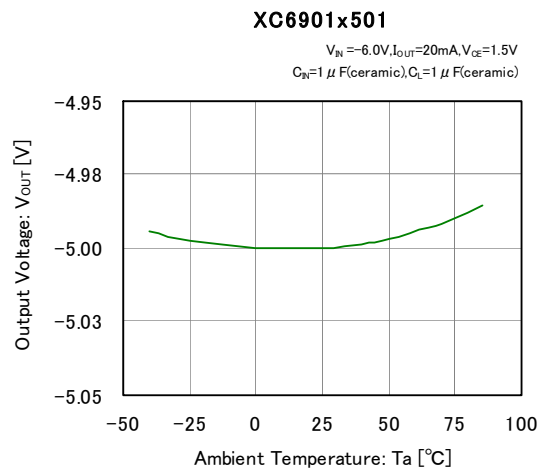
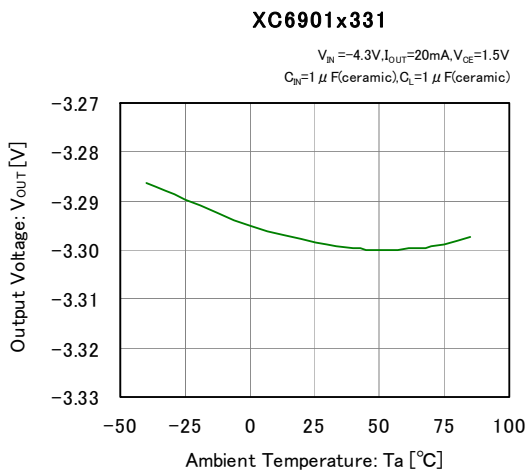


TYPICAL PERFORMANCE CHARACTERISTICS (Continued)

(4) Supply Current vs. Input Voltage (Continued)

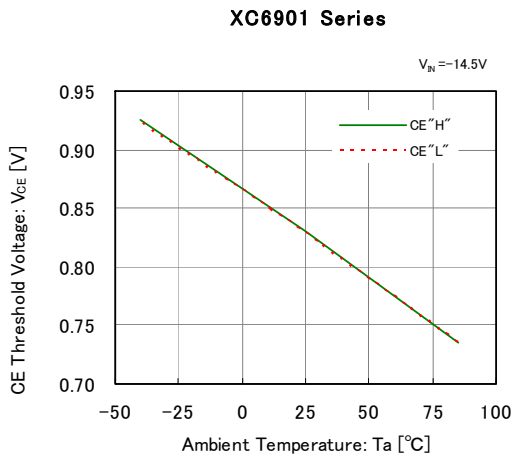


(5) Output Voltage vs. Ambient Temperature

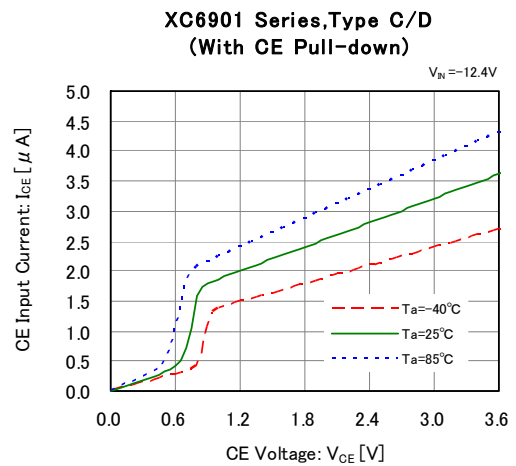
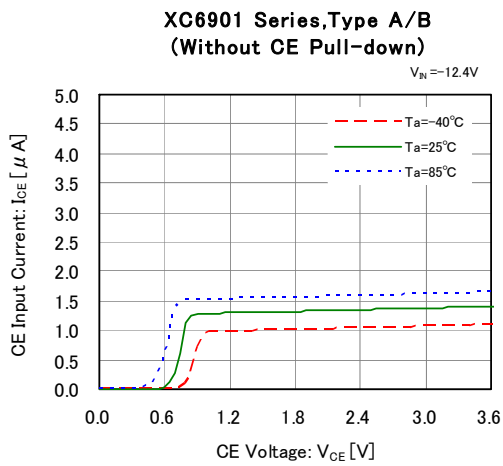


■ TYPICAL PERFORMANCE CHARACTERISTICS (Continued)

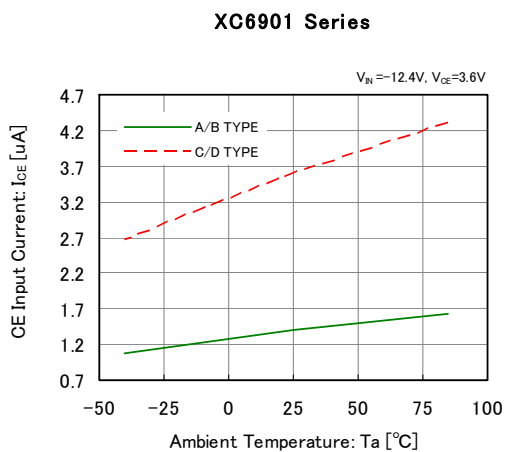
(6) CE Pin Threshold Voltage vs Ambient Temperature



(7) CE Input Current vs CE Voltage

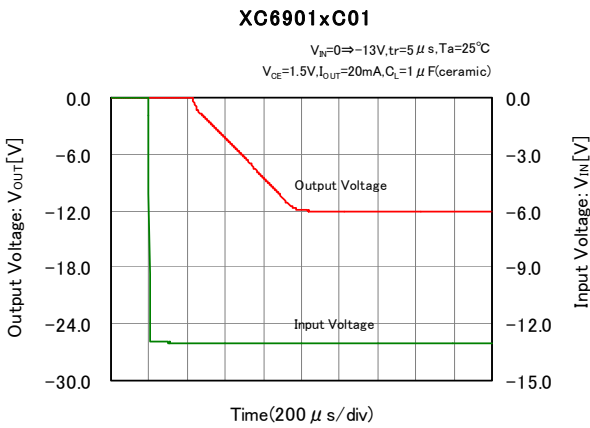
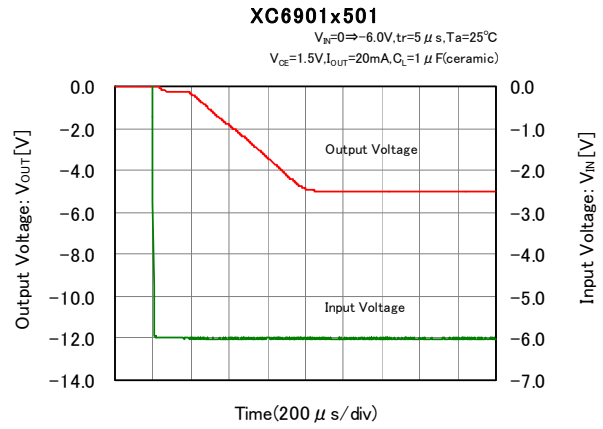
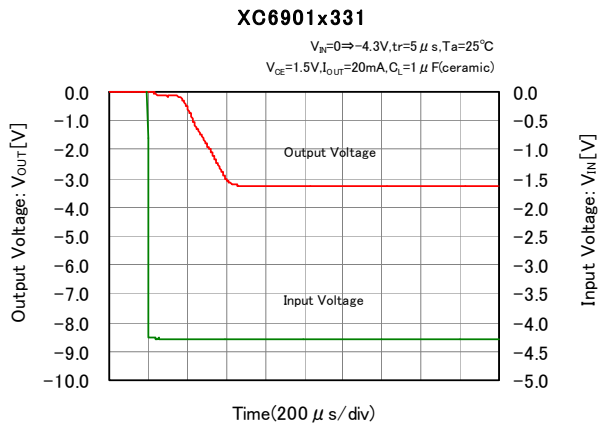


(8) CE Input Current vs Ambient Temperature

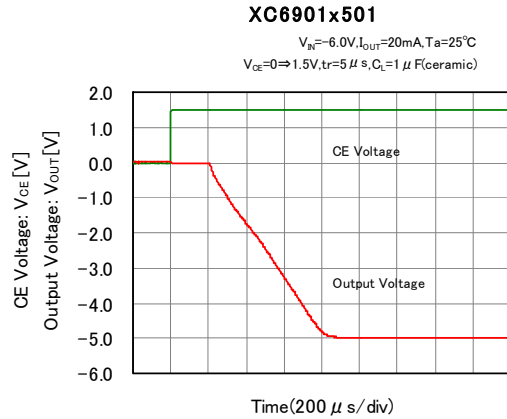
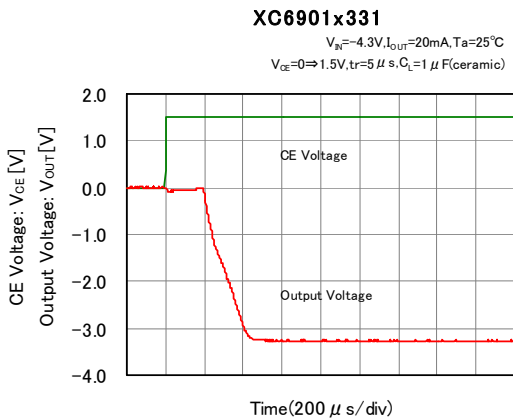


TYPICAL PERFORMANCE CHARACTERISTICS (Continued)

(9) Input Rising Response Time

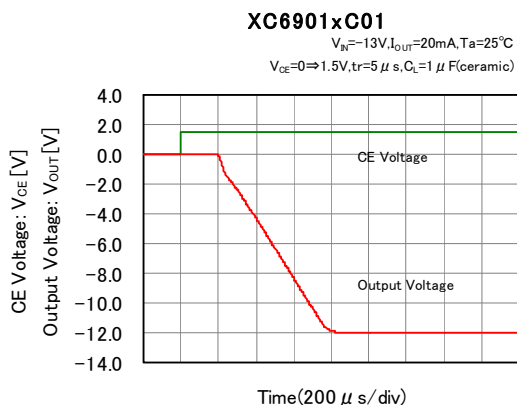


(10) CE Rising Response Time

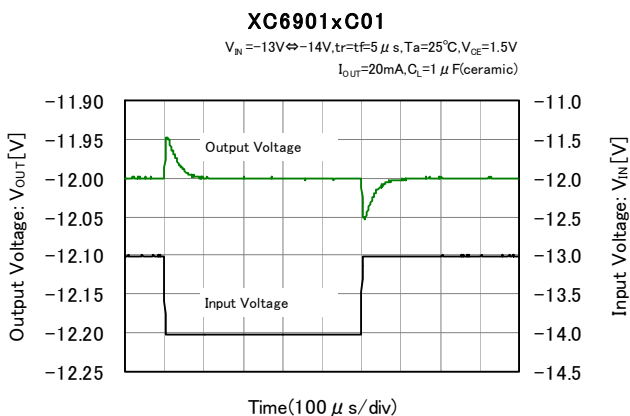
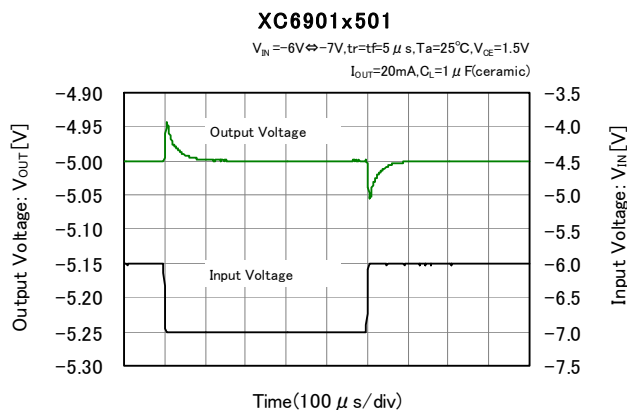
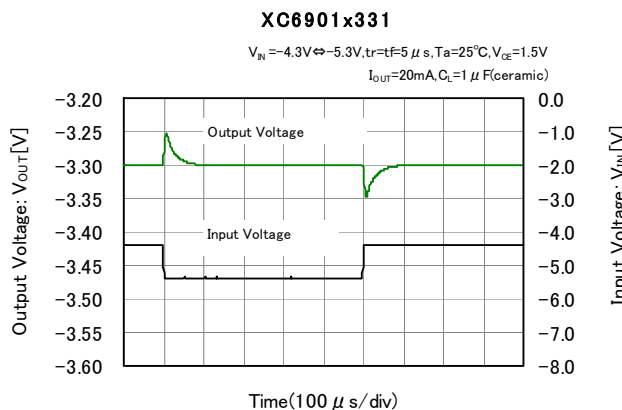


TYPICAL PERFORMANCE CHARACTERISTICS (Continued)

(10) CE Rising Response Time (Continued)



(11) Input Transient Response

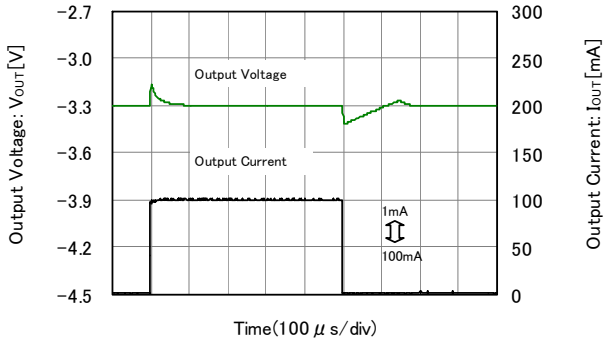


TYPICAL PERFORMANCE CHARACTERISTICS (Continued)

(12) Load Transient Response

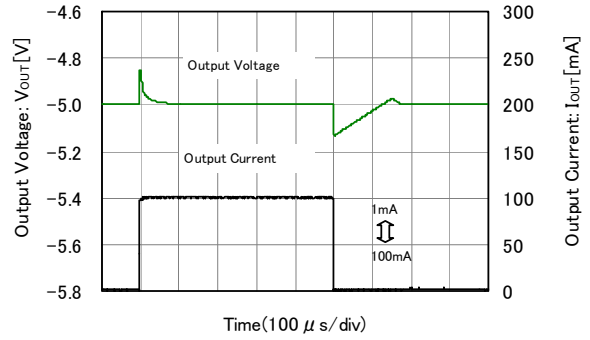
XC6901x331

$I_{OUT} = 1 \leftrightarrow 100\text{mA}$, $t_r = t_f = 5 \mu\text{s}$, $T_a = 25^\circ\text{C}$, $V_{CE} = 1.5\text{V}$
 $V_B = -4.3\text{V}$, $C_B = 1 \mu\text{F}$ (ceramic), $C_L = 1 \mu\text{F}$ (ceramic)



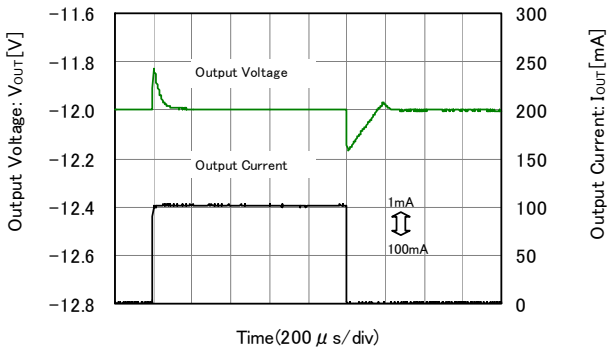
XC6901x501

$I_{OUT} = 1 \leftrightarrow 100\text{mA}$, $t_r = t_f = 5 \mu\text{s}$, $T_a = 25^\circ\text{C}$, $V_{CE} = 1.5\text{V}$
 $V_B = -6\text{V}$, $C_B = 1 \mu\text{F}$ (ceramic), $C_L = 1 \mu\text{F}$ (ceramic)



XC6901xC01

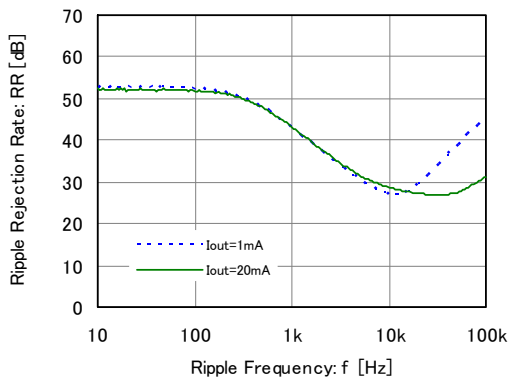
$I_{OUT} = 1 \leftrightarrow 100\text{mA}$, $t_r = t_f = 5 \mu\text{s}$, $T_a = 25^\circ\text{C}$, $V_{CE} = 1.5\text{V}$
 $V_B = -13\text{V}$, $C_B = 1 \mu\text{F}$ (ceramic), $C_L = 1 \mu\text{F}$ (ceramic)



(13) Ripple Rejection Rate

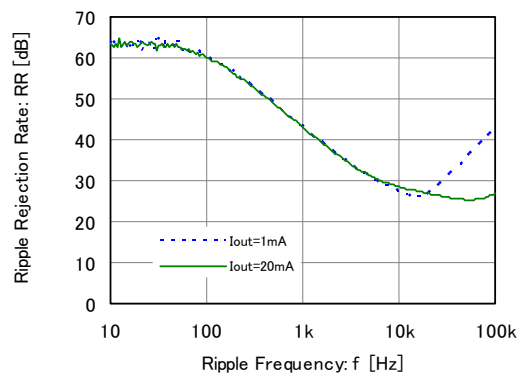
XC6901x331

$T_a = 25^\circ\text{C}$, $V_B = -4.3\text{V} + 0.5V_{F-PAC}$
 $V_{CE} = 1.5\text{V}$, $C_L = 1 \mu\text{F}$ (ceramic)



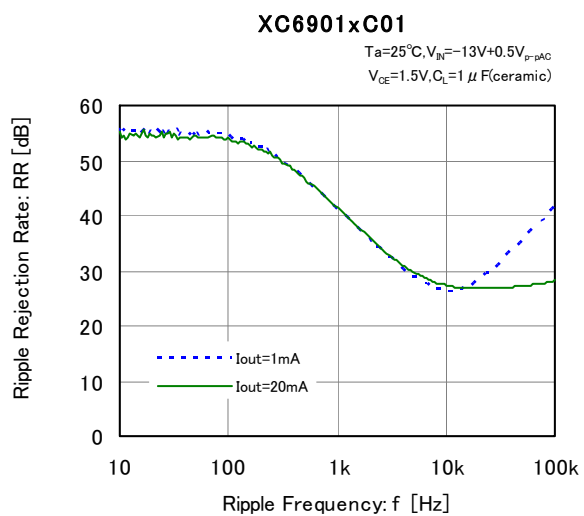
XC6901x501

$T_a = 25^\circ\text{C}$, $V_B = -6\text{V} + 0.5V_{F-PAC}$
 $V_{CE} = 1.5\text{V}$, $C_L = 1 \mu\text{F}$ (ceramic)



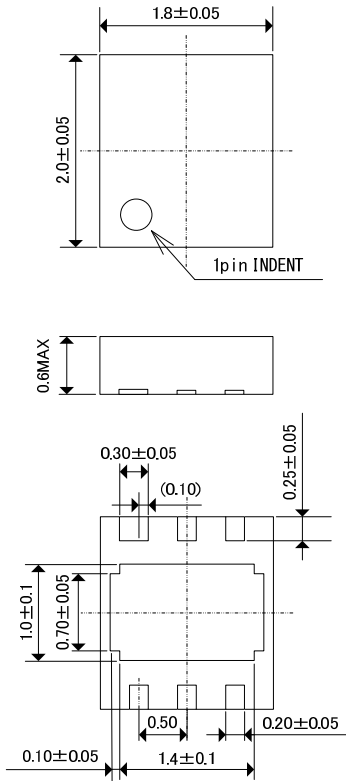
TYPICAL PERFORMANCE CHARACTERISTICS (Continued)

(13) Ripple Rejection Rate (Continued)

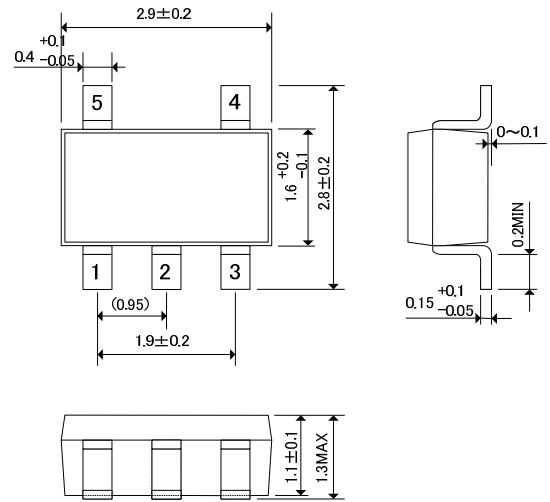


PACKAGING INFORMATION

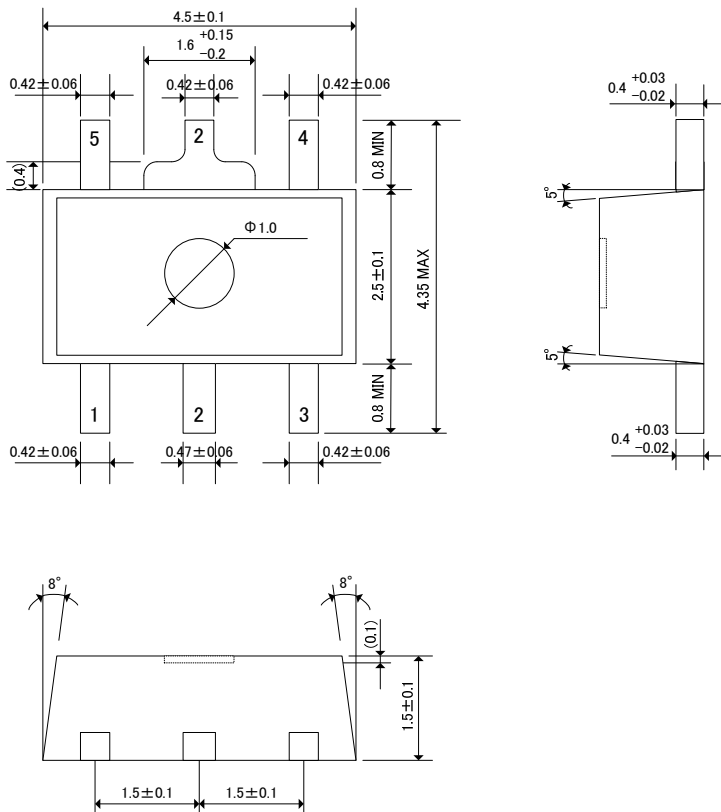
● USP-6C



● SOT-25

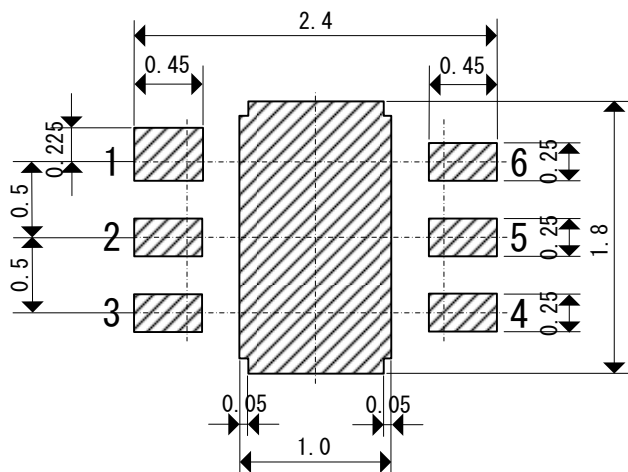


● SOT-89-5

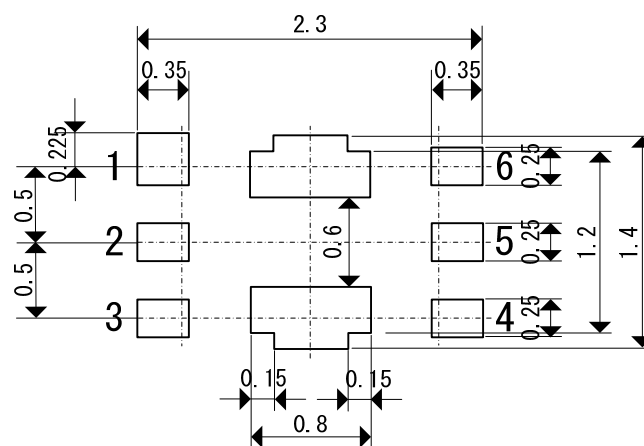


PACKAGING INFORMATION (Continued)

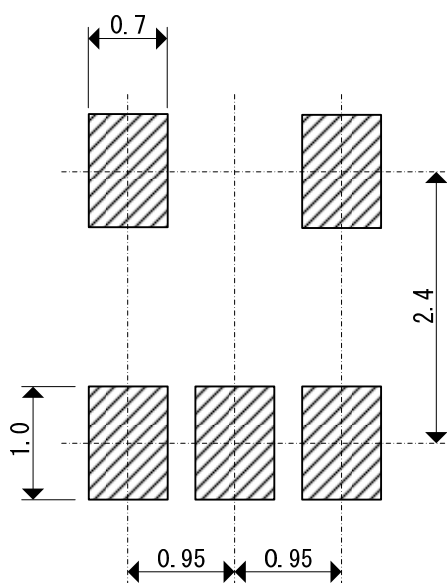
● USP-6C Reference Pattern Layout



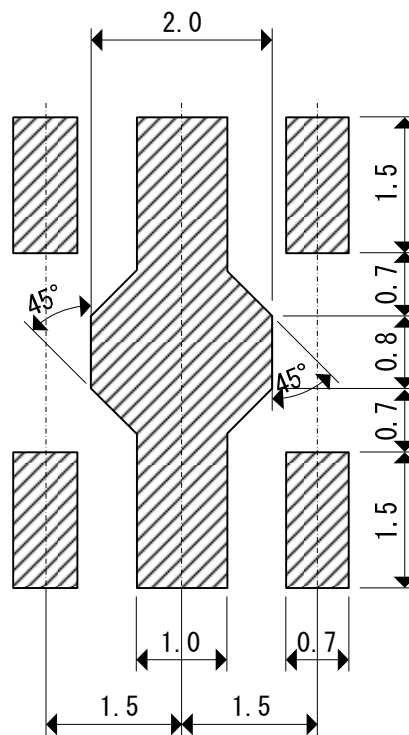
● USP-6C Reference Metal Mask Design



● SOT-25 Reference Pattern Layout



● SOT-89-5 Reference Pattern Layout



PACKAGING INFORMATION (Continued)

● SOT-25 Power Dissipation

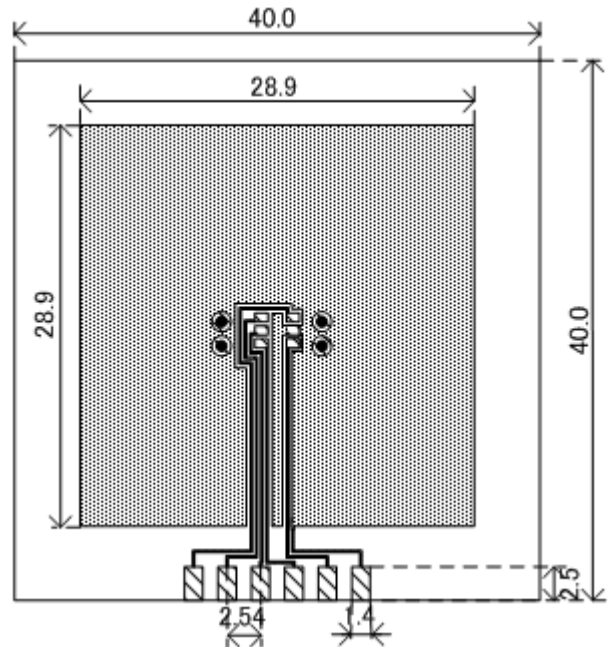
Power dissipation data for the SOT-25 is shown in this page.

The value of power dissipation varies with the mount board conditions.

Please use this data as one of reference data taken in the described condition.

1. Measurement Condition (Reference data)

- Condition: Mount on a board
- Ambient: Natural convection
- Soldering: Lead (Pb) free
- Board: Dimensions 40 x 40 mm (1600 mm² in one side)
Copper (Cu) traces occupy 50% of the board area
In top and back faces
Package heat-sink is tied to the copper traces
(Board of SOT-26 is used.)
- Material: Glass Epoxy (FR-4)
- Thickness: 1.6 mm
- Through-hole: 4 x 0.8 Diameter

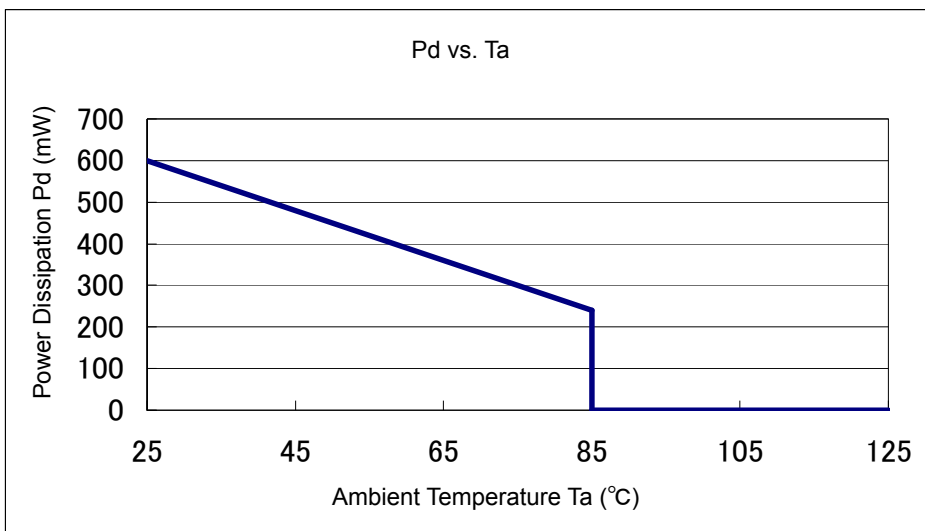


2. Power Dissipation vs. Ambient temperature

Evaluation Board (Unit: mm)

Board Mount ($T_j \text{ max} = 125^\circ\text{C}$)

| Ambient Temperature ($^\circ\text{C}$) | Power Dissipation Pd (mW) | Thermal Resistance ($^\circ\text{C}/\text{W}$) |
|------------------------------------------|---------------------------|--------------------------------------------------|
| 25 | 600 | 166.67 |
| 85 | 240 | |



■ PACKAGING INFORMATION (Continued)

● SOT-89-5 Power Dissipation

Power dissipation data for the SOT-89-5 is shown in this page.

The value of power dissipation varies with the mount board conditions.

Please use this data as one of reference data taken in the described condition.

2. Measurement Condition (Reference data)

Condition: Mount on a board

Ambient: Natural convection

Soldering: Lead (Pb) free

Board: Dimensions 40 x 40 mm (1600 mm² in one side)

Copper (Cu) traces occupy 50% of the board area

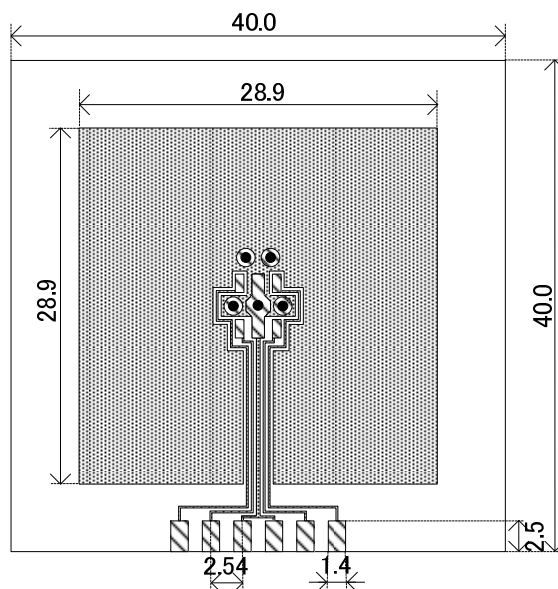
In top and back faces

Package heat-sink is tied to the copper traces

Material: Glass Epoxy (FR-4)

Thickness: 1.6 mm

Through-hole: 5 x 0.8 Diameter

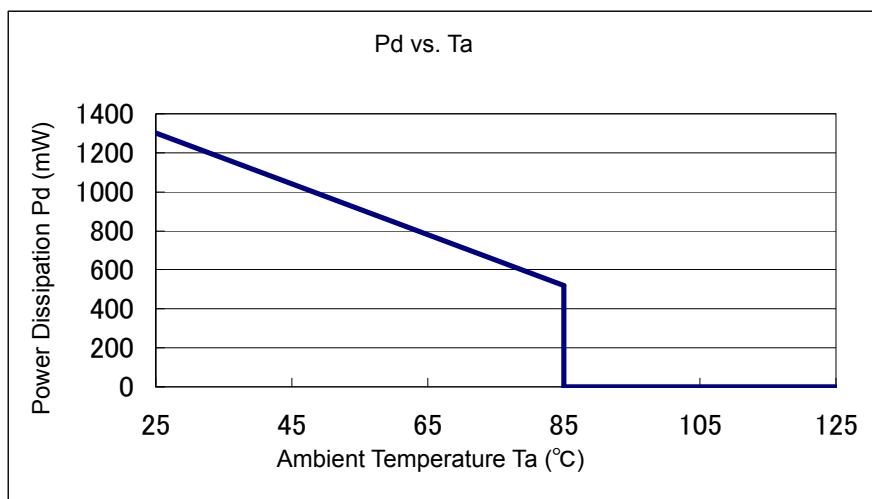


Evaluation Board (Unit: mm)

2. Power Dissipation vs. Ambient temperature

Board Mount ($T_j \text{ max} = 125^\circ\text{C}$)

| Ambient Temperature ($^\circ\text{C}$) | Power Dissipation Pd (mW) | Thermal Resistance ($^\circ\text{C}/\text{W}$) |
|------------------------------------------|---------------------------|--------------------------------------------------|
| 25 | 1300 | 76.92 |
| 85 | 520 | |



PACKAGING INFORMATION (Continued)

- USP-6C Power Dissipation

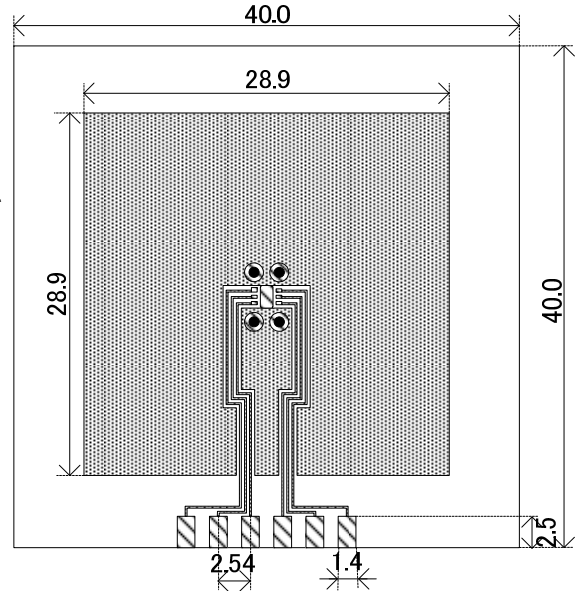
Power dissipation data for the USP-6C is shown in this page.

The value of power dissipation varies with the mount board conditions.

Please use this data as one of reference data taken in the described condition.

3. Measurement Condition (Reference data)

- Condition: Mount on a board
- Ambient: Natural convection
- Soldering: Lead (Pb) free
- Board: Dimensions 40 x 40 mm (1600 mm² in one side)
Copper (Cu) traces occupy 50% of the board area
In top and back faces
Package heat-sink is tied to the copper traces
- Material: Glass Epoxy (FR-4)
- Thickness: 1.6 mm
- Through-hole: 4 x 0.8 Diameter

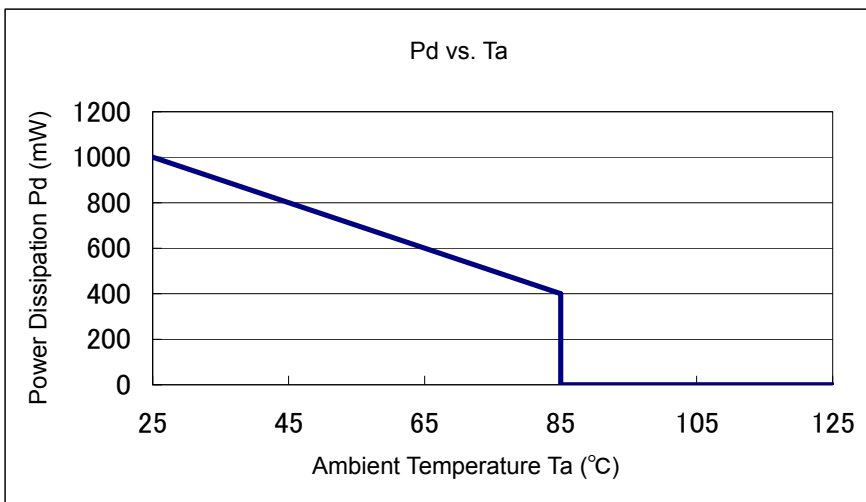


2. Power Dissipation vs. Ambient temperature

Board Mount ($T_j \text{ max} = 125^\circ\text{C}$)

Evaluation Board (Unit: mm)

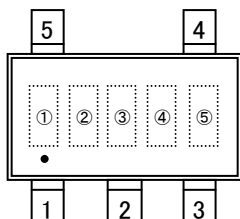
| Ambient Temperature ($^\circ\text{C}$) | Power Dissipation Pd (mW) | Thermal Resistance ($^\circ\text{C}/\text{W}$) |
|------------------------------------------|---------------------------|--------------------------------------------------|
| 25 | 1000 | 100.00 |
| 85 | 400 | |



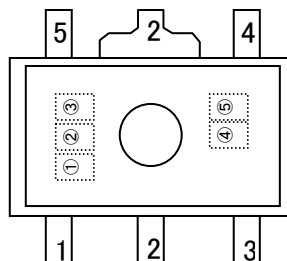
MARKING RULE

SOT-25(Under dot)

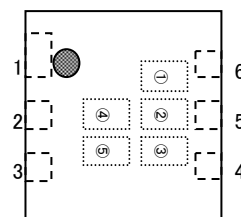
※A dot is marked below the mark of ①



SOT89-5



USP-6C



① represents product series

| MARK | PRODUCT SERIES |
|------|----------------|
| F | XC6901*****_G |

② represents output voltage range and product types

| MARK | OUTPUT VOLTAGE (V) | TYPE | PRODUCT SERIES |
|------|--------------------|------|---------------------------------|
| R | -0.9 ~ -3.8 | D | XC6901D091**-G ~ XC6901D381**-G |
| S | -3.9 ~ -6.8 | | XC6901D391**-G ~ XC6901D681**-G |
| T | -6.9 ~ -9.8 | | XC6901D691**-G ~ XC6901D981**-G |
| U | -9.9 ~ -12.0 | | XC6901D991**-G ~ XC6901DC01**-G |

③ represents output voltage

| MARK | OUTPUT VOLTAGE (V) | | | | MARK | OUTPUT VOLTAGE (V) | | | | MARK | OUTPUT VOLTAGE (V) | | | |
|------|--------------------|------|------|-------|------|--------------------|------|------|-------|------|--------------------|------|------|-------|
| 0 | -0.9 | -3.9 | -6.9 | -9.9 | A | -1.9 | -4.9 | -7.9 | -10.9 | N | -2.9 | -5.9 | -8.9 | -11.9 |
| 1 | -1.0 | -4.0 | -7.0 | -10.0 | B | -2.0 | -5.0 | -8.0 | -11.0 | P | -3.0 | -6.0 | -9.0 | -12.0 |
| 2 | -1.1 | -4.1 | -7.1 | -10.1 | C | -2.1 | -5.1 | -8.1 | -11.1 | R | -3.1 | -6.1 | -9.1 | - |
| 3 | -1.2 | -4.2 | -7.2 | -10.2 | D | -2.2 | -5.2 | -8.2 | -11.2 | S | -3.2 | -6.2 | -9.2 | - |
| 4 | -1.3 | -4.3 | -7.3 | -10.3 | E | -2.3 | -5.3 | -8.3 | -11.3 | T | -3.3 | -6.3 | -9.3 | - |
| 5 | -1.4 | -4.4 | -7.4 | -10.4 | F | -2.4 | -5.4 | -8.4 | -11.4 | U | -3.4 | -6.4 | -9.4 | - |
| 6 | -1.5 | -4.5 | -7.5 | -10.5 | H | -2.5 | -5.5 | -8.5 | -11.5 | V | -3.5 | -6.5 | -9.5 | - |
| 7 | -1.6 | -4.6 | -7.6 | -10.6 | K | -2.6 | -5.6 | -8.6 | -11.6 | X | -3.6 | -6.6 | -9.6 | - |
| 8 | -1.7 | -4.7 | -7.7 | -10.7 | L | -2.7 | -5.7 | -8.7 | -11.7 | Y | -3.7 | -6.7 | -9.7 | - |
| 9 | -1.8 | -4.8 | -7.8 | -10.8 | M | -2.8 | -5.8 | -8.8 | -11.8 | Z | -3.8 | -6.8 | -9.8 | - |

④,⑤ represents production lot number

01~09, 0A~0Z, 11~9Z, A1~A9, AA~AZ, B1~ZZ repeated

(G, I, J, O, Q, W excluded)

*No character inversion used.

1. The products and product specifications contained herein are subject to change without notice to improve performance characteristics. Consult us, or our representatives before use, to confirm that the information in this datasheet is up to date.
2. We assume no responsibility for any infringement of patents, patent rights, or other rights arising from the use of any information and circuitry in this datasheet.
3. Please ensure suitable shipping controls (including fail-safe designs and aging protection) are in force for equipment employing products listed in this datasheet.
4. The products in this datasheet are not developed, designed, or approved for use with such equipment whose failure or malfunction can be reasonably expected to directly endanger the life of, or cause significant injury to, the user.
(e.g. Atomic energy; aerospace; transport; combustion and associated safety equipment thereof.)
5. Please use the products listed in this datasheet within the specified ranges.
Should you wish to use the products under conditions exceeding the specifications, please consult us or our representatives.
6. We assume no responsibility for damage or loss due to abnormal use.
7. All rights reserved. No part of this datasheet may be copied or reproduced without the prior permission of TOREX SEMICONDUCTOR LTD.

TOREX SEMICONDUCTOR LTD.

单击下面可查看定价，库存，交付和生命周期等信息

[>>Torex Semiconductor\(特瑞仕\)](#)